



(2,16 mm) .085"

DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:
DPAF

DPAF Mates with:
DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material: Black LCP

Contact Material: Copper Alloy

Plating:

Au over 50µ" (1,27 µm) Ni

Current Rating (2x3): 2.9 A per pin

Operating Temp Range: -55°C to +125°C

Contact Resistance: 10.4mΩ

Working Voltage: 300 VAC

Mated Cycles: 100 Cycles

RoHS Compliant: Yes

Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Protocols Supported

- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™
- XAUI
- MGT (Rocket I/O)

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings
- Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

DPAM

PAIRS PER ROW

07.0

PLATING OPTION

NO. OF ROWS

SOLDER TYPE

A

OPTION

-04, -06
-08, -15, -23

-S
=30µ" (0,76 µm)
Gold on contact area,
Tin on solder tail

-8
=Eight
Pair
Rows

-3
=Three
Pair
Rows

-2
= Lead-Free
Tin Alloy
96.5% Sn/
3% Ag/.5% Cu
Solder Crimp

-K
=(20,00 mm) 0.80"
DIA Polyimide
film Pick &
Place Pad

-TR
=Tape & Reel

-GP
=Guide Post
(-23 only)

NO OF ROWS	A
-8	(24,59) .968
-3	(11,89) .468

DPAM/DPAF 10 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	7 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB. Complete test data available at www.samtec.com?DPAM, www.samtec.com?DPAF or contact sig@samtec.com

DPAF

PAIRS PER ROW

03.0

PLATING OPTION

NO. OF ROWS

SOLDER TYPE

A

OPTION

-04, -06, -08,
-15, -23

-S
=30µ" (0,76 µm)
Gold on contact area,
Tin on solder tail

-8
=Eight
Pair
Rows

-3
=Three
Pair
Rows

-2
= Lead-Free Tin Alloy
96.5% Sn/ 3%Ag/
.5% Cu
Solder Crimp

-K
=(20,00 mm)
0.80" DIA
Polyimide
film
Pick &
Place Pad

-TR
=Tape & Reel

NO OF ROWS	A
-8	(23,32) .918
-3	(10,62) .418

NO OF ROWS	A	SIZE	USABLE PAIRS PER ARRAY*
-8	(23,32) .918	-04 x -3	6 Pairs
-8	(23,32) .918	-06 x -3	12 Pairs
-8	(23,32) .918	-04 x -8	16 Pairs
-8	(23,32) .918	-06 x -8	32 Pairs
-8	(23,32) .918	-08 x -8	48 Pairs
-8	(23,32) .918	-15 x -8	104 Pairs
-8	(23,32) .918	-23 x -8	168 Pairs
-3	(10,62) .418	-08 x -3	18 Pairs
-3	(10,62) .418	-15 x -3	39 Pairs
-3	(10,62) .418	-23 x -3	63 Pairs

DPAM LEAD STYLE	DPAF MATED HEIGHT*
-07.0	10 mm

*Processing conditions will affect mated height.

*Assumes first and last pair in each row are grounded

Due to technical progress, all designs, specifications and components are subject to change without notice.

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